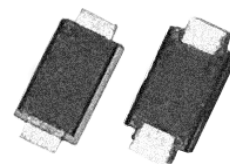


Surface Mount General Purpose Silicon Rectifiers

Reverse Voltage - 50 to 1000 V

Forward Current - 1 A



FEATURES

- For surface mounted applications
- Low profile package
- Glass Passivated Chip Junction
- Ideal for automated placement
- Lead free in comply with EU RoHS 2011/65/EU directives
- Marking: A1-A7

MECHANICAL DATA

- Case: SOD-123FL
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 15mg / 0.00053oz

Maximum Ratings and Electrical characteristics

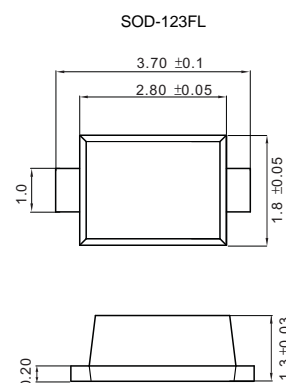
Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Functional Diagram



Dimensions



Parameter	Symbols	1N4001W	1N4002W	1N4003W	1N4004W	1N4005W	1N4006W	1N4007W	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current at $T_c = 125\text{ °C}$	$I_{F(AV)}$	1							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load	I_{FSM}	30							A
Maximum Instantaneous Forward Voltage at 1 A	V_F	1.1							V
Maximum DC Reverse Current $T_a = 25\text{ °C}$ at Rated DC Blocking Voltage $T_a = 125\text{ °C}$	I_R	5 50							μA
Typical Junction Capacitance ⁽¹⁾	C_j	11							pF
Typical Thermal Resistance ⁽²⁾	$R_{\theta JA}$	90							°C/W
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150							°C

(1) Measured at 1 MHz and applied reverse voltage of 4 V D.C

(2) P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

Fig.1 Forward Current Derating Curve

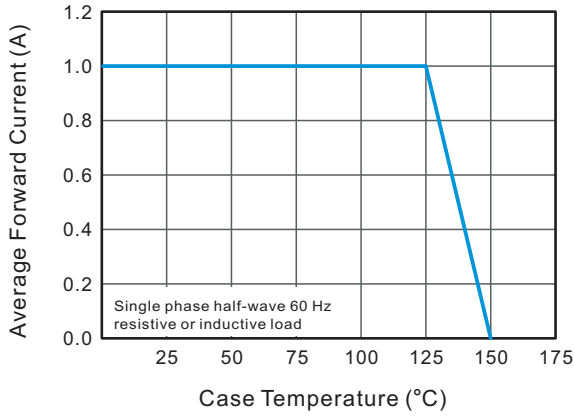


Fig.2 Typical Instantaneous Reverse Characteristics

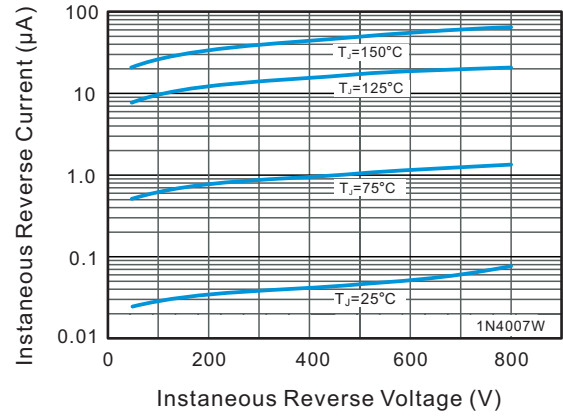


Fig.3 Typical Forward Characteristic

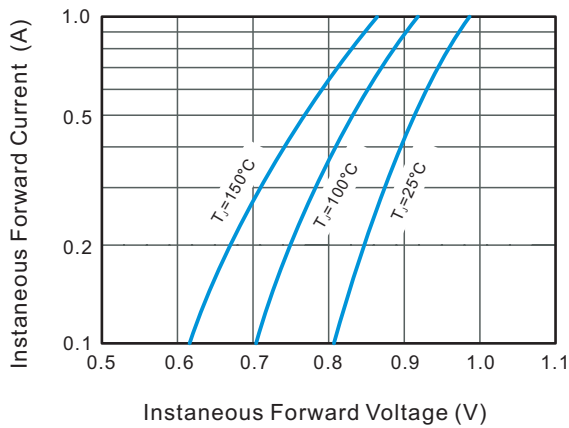


Fig.4 Typical Junction Capacitance

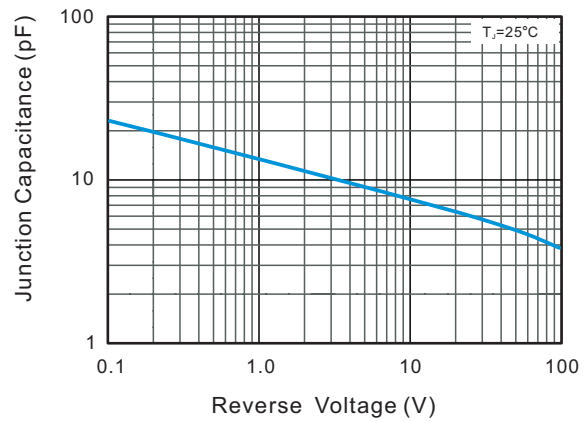
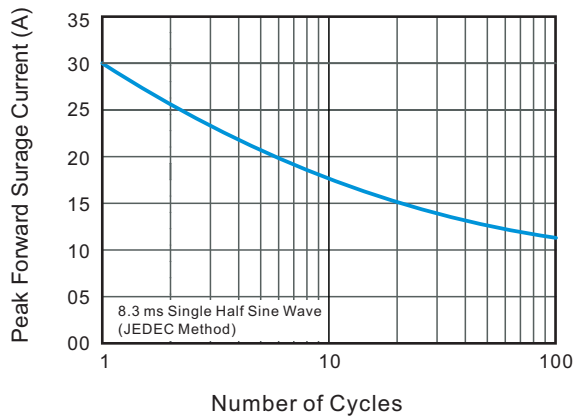
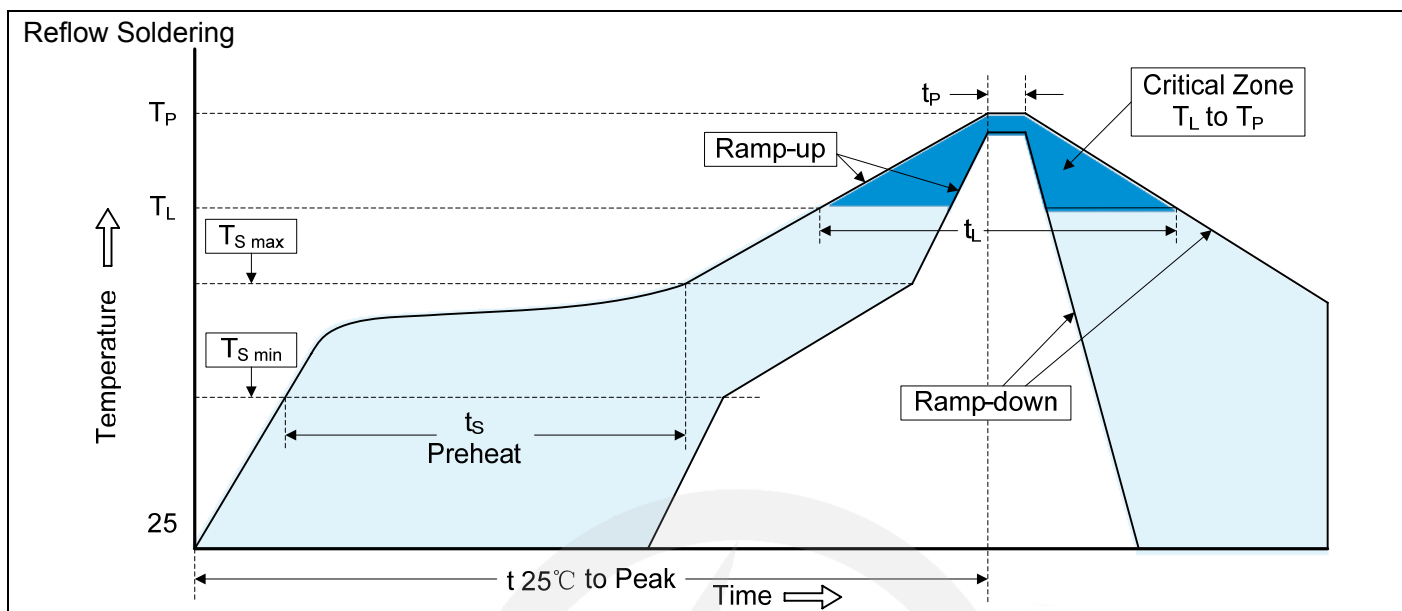


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current



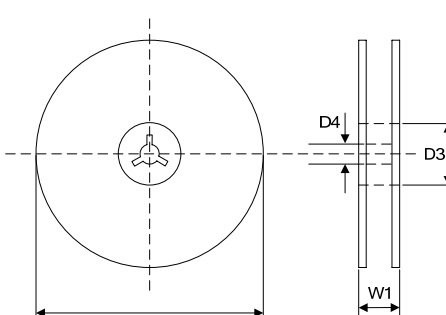
Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T_L to T_P)	3°C/second max.
Preheat -Temperature Min ($T_{S\ min}$) -Temperature Max ($T_{S\ max}$) -Time (min to max) (t_s)	150°C 200°C 60-180 seconds
$T_{S\ max}$ to T_L -Ramp-up Rate	3°C/second max.
Time maintained above: -Temperature (T_L) -Time (t_L)	217°C 60-150 seconds
Peak Temperature (T_P)	260°C
Time within 5°C of actual Peak Temperature (t_P)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

Packaging

7" Reel 	D2	Φ178.0±2.0
	D3	Φ50.0Min.
	D4	Φ13.0±0.5
	W1	16.0±2.0
	Quantity: 3000PCS	